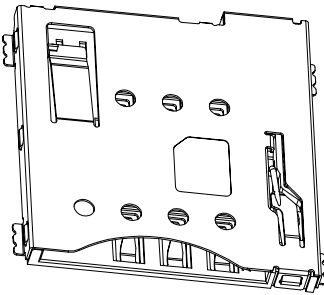


ROHS

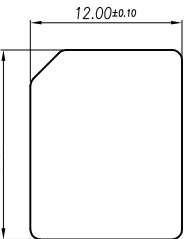
REV.	Q'TY	ECN. NO.	APR.	DATE
A		FIRST RELEASE	Yann	2023.04.22

4.30±0.30 CARD EJECT POSITION
1.00±0.30 CARD LOCK POSITION
0.20±0.30 PUSH STROKE POSITION

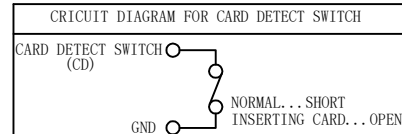
- Notes:
- Material:
Housing: High Temperature Thermoplastic.
Terminal: Copper Alloy
Shell: Stainless Steel
 - Plating:
Terminal: 50u" Ni Underplated Overall
G/F Plated On Contact Area
G/F Plated On Solder Area
Shell: 30u" Ni Underplated Overall
G/F Plated On Contact Area And Solder Area
 - Technical Speciality:
Rated Voltage: 30V
Current Rating: 0.5A
Insulation Resistance: 1000MΩ Min.
Contact Resistance: 100mΩ Max.
Withstanding Voltage: 500V DC For 1 Minutes.
Operating Temperature: -40℃~+85℃ Humidity 80% R.H Max.



3D VIEW



CARD SIZE



- SMT SOLDER AREA
 - COPPER RESTRICTED AREA
1. TOUCH AREA OF CONTACT TIPS NO ELECTRICAL FUNCTION
2. NO FIRST PCB_LAYOUT CIRCUITS IN THE AREA

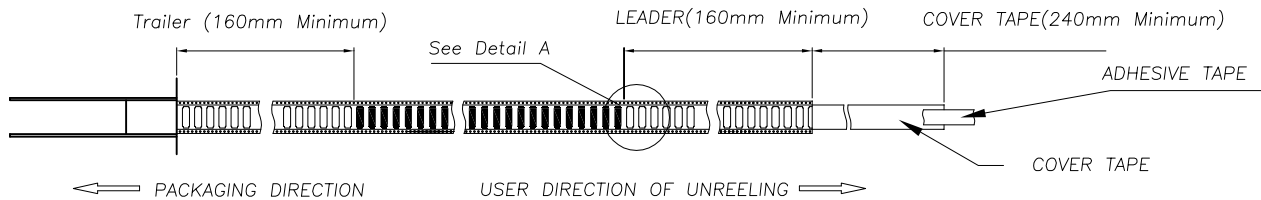
PIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
CD	Detect Switch

DIMENSION IN mm			Dongguan JianXing Electronics Co., Ltd.	
TOLERANCE UNLESS OTHERWISE SPECIFIED				
.X±0.35	X.*± 5°	APR.	TITLE: 1.50H Micro_SIM Card CONNECTOR	
.XX±0.25	.X.*± 3°	CHK.	DWG NO. SM006-1B150A061	
.XXX±0.15	.XX.*± 1°	DRA. Yann 2023.04.22	CUSTOMER DRAWING	
SIZE A4	SCALE 4:1	SHEET 1/2	REV. A	

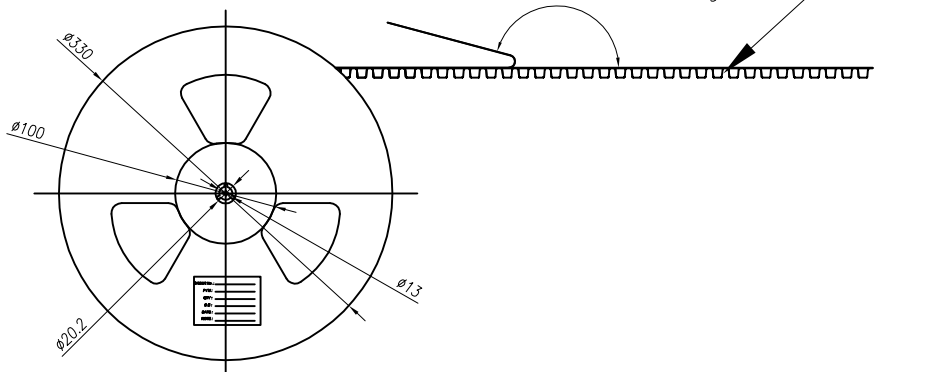
RECOMMENDED PCB LAYOUT
TOLERANCE: ±0.05

ROHS

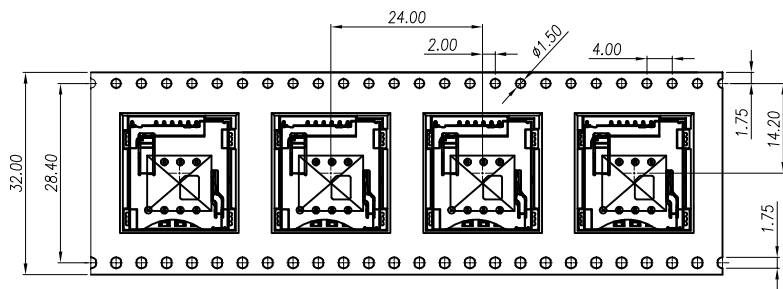
REV.	Q'TY	ECN. NO.	APR.	DATE
A		FIRST RELEASE	Yann	2024.04.22



COVER TAPE PEELING ANGLE: 165°~180°
PEELING FORCE: 20~130g





PACKAGING DIRECTION ← → USER DIRECTION OF UNREELING



DETAIL A
1:4

ITEM	PRODUCT NO	QTY/REEL	REEL/CARTON	QTY/CARTON	CARTON SIZE
1	SM006-1B150A061	1000	10	10000	350X350X340

DIMENSION IN mm		 Dongguan JianXing Electronics Co.,Ltd.		
TOLERANCE UNLESS OTHERWISE SPECIFIED		APR.	TITLE: 1.50H Micro_SIM Card CONNECTOR	
.X±0.35	.X*± 5°	CHK.	DWG NO. SM006-1B150A061	
.XX±0.25	.X*± 3°	DRA Yann	PROJ. 	CUSTOMER DRAWING
.XXX±0.15	.XX*± 1°	2024.04.22	SIZE A4	SCALE 4:1
			SHEET 2/2	REV. A